

RESIN COMPOSITION AND MOLDED ARTICLE

ABSTRACT

An object of the present invention is to provide a resin composition and a molded article each having suppressed
5 surface stickiness while having high stress-relaxing ability and vibration-absorbing ability at room temperature. A resin composition (X) containing 10 to 50 parts by mass of a thermoplastic resin (A) and 50 to 90 parts by mass of an inorganic substance (B), wherein a $\tan \delta$ peak temperature and
10 $\tan \delta$ peak value, obtained by performing dynamic viscoelastic measurement at a frequency of 10 rad/s (1.6 Hz) in the temperature range of -40 to 150°C, are 0°C or higher and 60°C or lower, and 0.8 or more and 5.0 or less, respectively.

[No available figure]